Silicon P-Channel MOS FET

# HITACHI

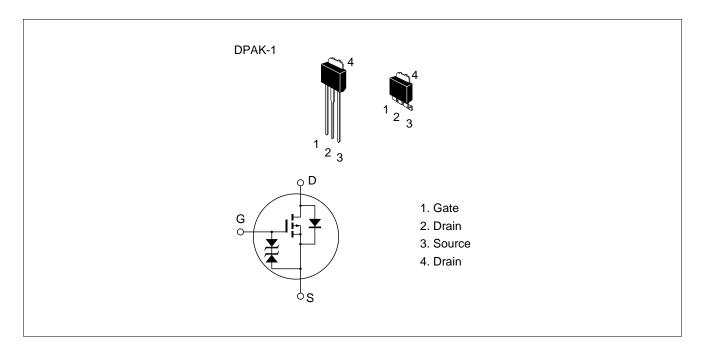
## Application

High speed power switching

## Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator, DC-DC converter

## Outline





## **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	-200	V
Gate to source voltage	V <sub>GSS</sub>	±20	V
Drain current	I <sub>D</sub>	-3	А
Drain peak current	l <mark>★1</mark> D(pulse)	-12	А
Body to drain diode reverse drain current	I <sub>DR</sub>	-3	А
Channel dissipation	Pch*2	20	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1.  $PW \le 10 \ \mu s$ , duty cycle  $\le 1\%$ 

2. Value at  $T_c = 25^{\circ}C$ 

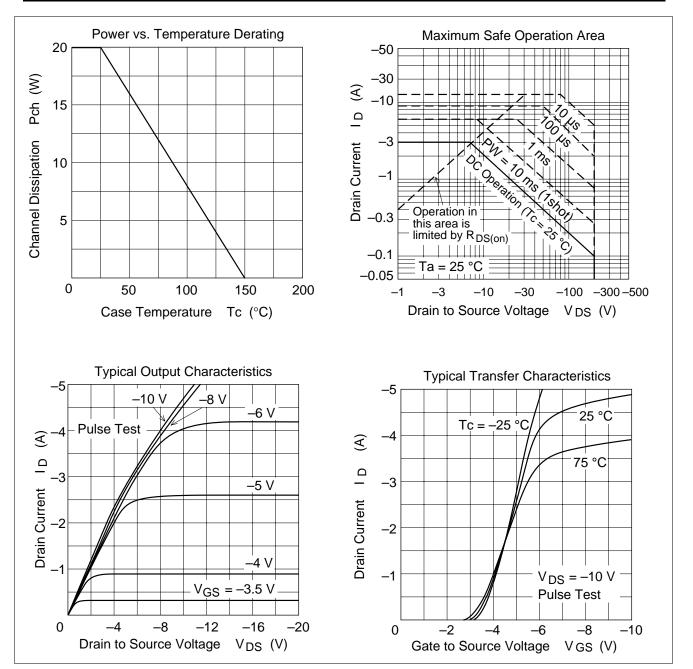
#### **Electrical Characteristics** (Ta = 25°C)

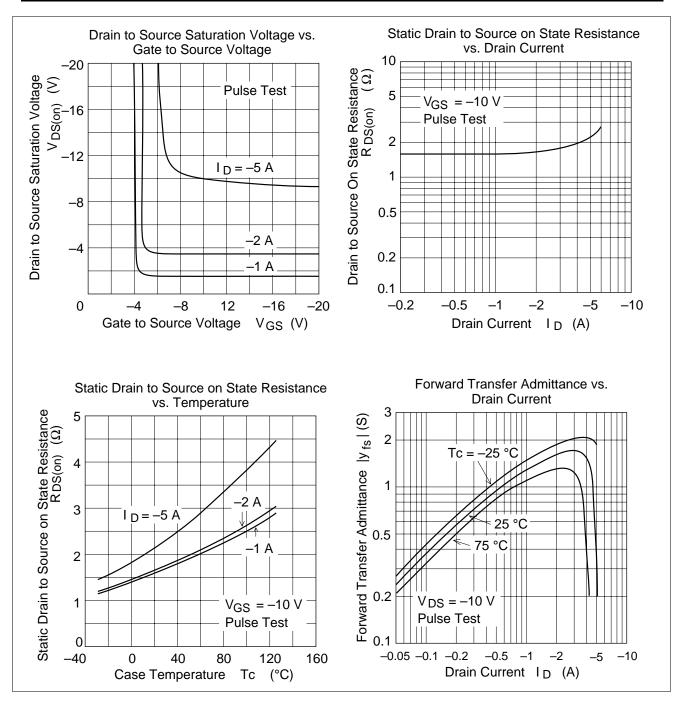
Item	Symbol	Min	Тур	Max	Unit	Test conditions	
Drain to source breakdown voltage	$V_{(BR)DSS}$	-200	_	_	V	$I_{\rm D} = -10$ mA, $V_{\rm GS} = 0$	
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	—	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$	
Gate to source leak current	I <sub>GSS</sub>	_	_	±10	μA	$V_{GS} = \pm 16 \text{ V}, \text{ V}_{DS} = 0$	
Zero gate voltage drain current	I <sub>DSS</sub>	_		-100	μA	$V_{\rm DS} = -160 \text{ V}, \text{ V}_{\rm GS} = 0$	
Gate to source cutoff voltage	$V_{GS(off)}$	-2.0		-4.0	V	$I_{\rm D} = -1 \text{ mA}, V_{\rm DS} = -10 \text{ V}$	
Static drain to source on state resistance	$R_{\text{DS(on)}}$	—	1.7	2.3	Ω	$I_{\rm D} = -2$ A, $V_{\rm GS} = -10$ V <sup>*1</sup>	
Forward transfer admittance	y <sub>fs</sub>	1.0	1.7	_	S	$I_{\rm D} = -2$ A, $V_{\rm DS} = -10$ V <sup>*1</sup>	
Input capacitance	Ciss	—	330	—	pF	$V_{DS} = -10 V, V_{GS} = 0,$	
Output capacitance	Coss	_	130	_	pF	f = 1 MHz	
Reverse transfer capacitance	Crss	_	25	_	pF		
Turn-on delay time	t <sub>d(on)</sub>	—	10	—	ns	$I_{\rm D} = -2$ A, $V_{\rm GS} = -10$ V,	
Rise time	t <sub>r</sub>	_	30	_	ns	R <sub>L</sub> = 15 Ω	
Turn-off delay time	t <sub>d(off)</sub>	_	40	_	ns		
Fall time	t <sub>f</sub>	_	30	_	ns		
Body to drain diode forward voltage	$V_{\text{DF}}$	_	-1.15	_	V	$I_{\rm F} = -3$ A, $V_{\rm GS} = 0$	
Body to drain diode reverse recovery time	t <sub>rr</sub>	—	180	—	ns	$I_{\rm F} = -3$ A, $V_{\rm GS} = 0$ , $di_{\rm F}/dt = 50$ A/µs	
Noto: 1 Dulas test							

Note: 1. Pulse test

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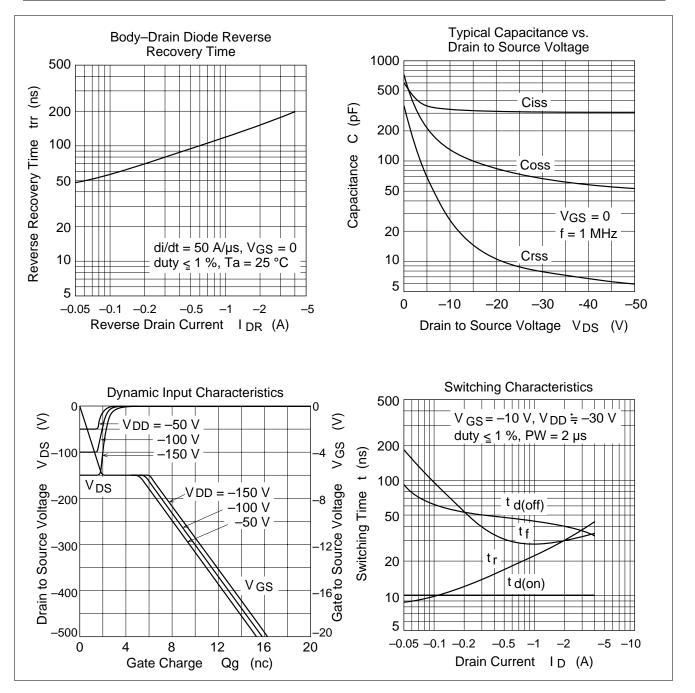
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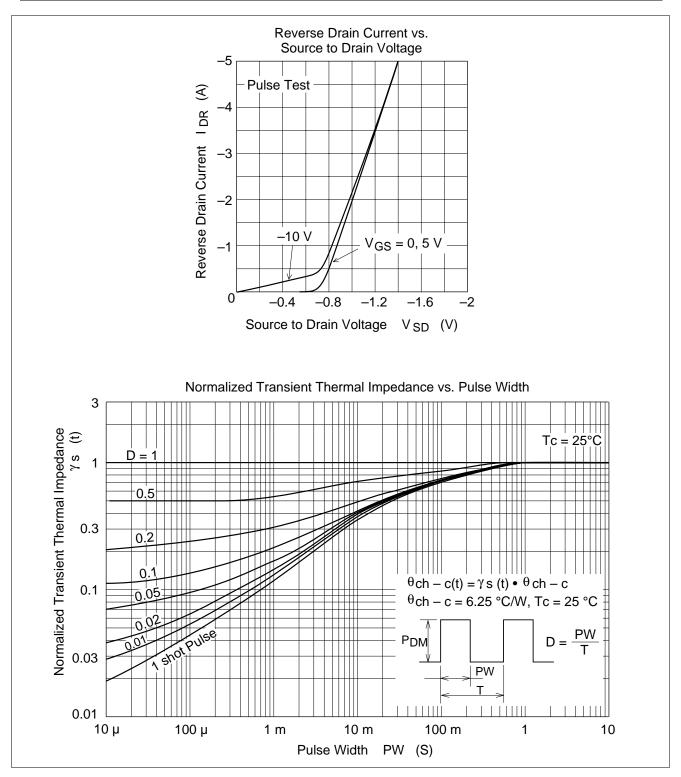




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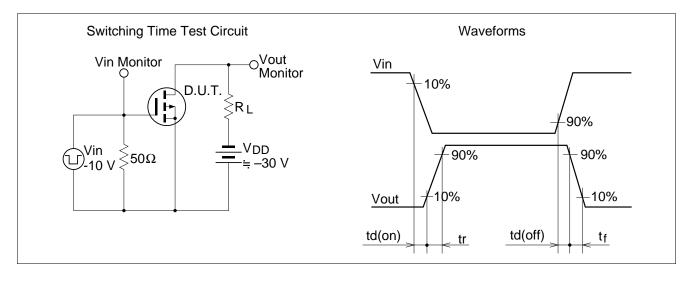
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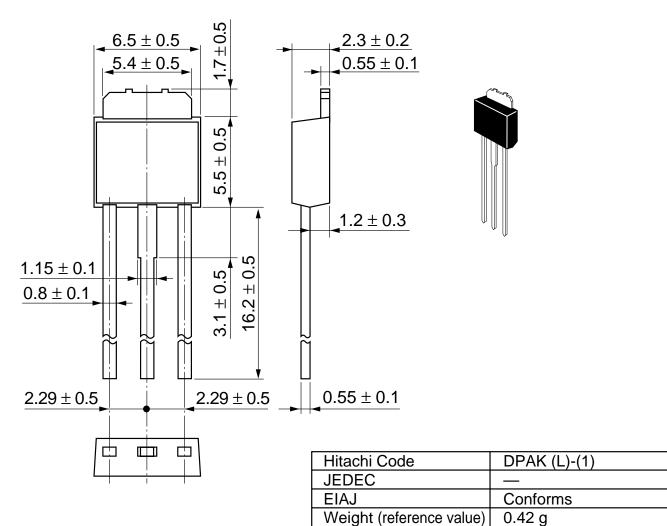


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Unit: mm



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